

|                                   |  |                         |                                                           |             |
|-----------------------------------|--|-------------------------|-----------------------------------------------------------|-------------|
| <b>Notice of References Cited</b> |  | Application/Control No. | Applicant(s)/Patent Under Reexamination<br>USAMI, TATSUYA |             |
|                                   |  | Examiner                | Art Unit                                                  | Page 1 of 1 |
| <b>U.S. PATENT DOCUMENTS</b>      |  |                         |                                                           |             |

| * |   | Document Number<br>Country Code-Number-Kind Code | Date<br>MM-YYYY | Name           | Classification |
|---|---|--------------------------------------------------|-----------------|----------------|----------------|
| * | A | US-6,054,379                                     | 04-2000         | Yau et al.     | 438/623        |
| * | B | US-6,333,257                                     | 12-2001         | Aoi, Nobuo     | 438/626        |
| * | C | US-6,218,317                                     | 04-2001         | Allada et al.  | 438/780        |
| * | D | US-2005/0233591 A1                               | 10-2005         | Schmitt et al. | 438/706        |
| * | E | US-6,008,540                                     | 12-1999         | Lu et al.      | 257/758        |
|   | F | US-                                              |                 |                |                |
|   | G | US-                                              |                 |                |                |
|   | H | US-                                              |                 |                |                |
|   | I | US-                                              |                 |                |                |
|   | J | US-                                              |                 |                |                |
|   | K | US-                                              |                 |                |                |
|   | L | US-                                              |                 |                |                |
|   | M | US-                                              |                 |                |                |

**FOREIGN PATENT DOCUMENTS**

| * |   | Document Number<br>Country Code-Number-Kind Code | Date<br>MM-YYYY | Country | Name | Classification |
|---|---|--------------------------------------------------|-----------------|---------|------|----------------|
|   | N |                                                  |                 |         |      |                |
|   | O |                                                  |                 |         |      |                |
|   | P |                                                  |                 |         |      |                |
|   | Q |                                                  |                 |         |      |                |
|   | R |                                                  |                 |         |      |                |
|   | S |                                                  |                 |         |      |                |
|   | T |                                                  |                 |         |      |                |

**NON-PATENT DOCUMENTS**

| * |   | Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)                                                                                                                                             |
|---|---|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
|   | U | Chen et al., Effects of Slurry formulations on chemical-mechanical polishing of low dielectric constant polysiloxanes: hydrido-organo siloxane and methyl silsesquioxane; J. Vac. Sci. Technol. B 18(1), Jan/Feb 2000, pages 201-207. |
|   | V |                                                                                                                                                                                                                                       |
|   | W |                                                                                                                                                                                                                                       |
|   | X |                                                                                                                                                                                                                                       |

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.